

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT3351359

<b>SUBMISSION TYPE:</b>	CORRECTIVE ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	Corrective Assignment to correct the ASSIGNORS previously recorded on Reel 035055 Frame 0738. Assignor(s) hereby confirms the FOLLOWING ASSIGNORS SHOULD BE ADDED TO NOTICE OF RECORDATION: KANG, MIN WOO; KIM, HYUN A..

## CONVEYING PARTY DATA

Name	Execution Date
JONG MIN JANG	01/21/2015
JONG HYEON CHAE	01/21/2015
JOON SUP LEE	01/21/2015
DAEWOONG SUH	02/02/2015
WON YOUNG ROH	01/21/2015
MIN WOO KANG	01/21/2015
HYUN A KIM	01/21/2015

## RECEIVING PARTY DATA

<b>Name:</b>	SEOUL VIOSYS CO., LTD.
<b>Street Address:</b>	65-16, SANDAN-RO 163 BEON-GIL
<b>Internal Address:</b>	DANWON-GU, GYEONGGI-DO
<b>City:</b>	ANSAN-SI
<b>State/Country:</b>	KOREA, REPUBLIC OF

## PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14420175

## CORRESPONDENCE DATA

**Fax Number:** (858)720-5819  
*Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.*

**Phone:** (858)720-5700  
**Email:** michellemelendez@perkinscoie.com  
**Correspondent Name:** BING AI  
**Address Line 1:** PERKINS COIE LLP  
**Address Line 2:** PO BOX 1247  
**Address Line 4:** SEATTLE, WASHINGTON 98111-1247

<b>ATTORNEY DOCKET NUMBER:</b>	114896-8031.US00
<b>NAME OF SUBMITTER:</b>	MICHELLE MELENDEZ

PATENT

<b>SIGNATURE:</b>	/Michelle Melendez/
<b>DATE SIGNED:</b>	05/13/2015
<b>Total Attachments: 13</b> source=Corrective Assignment#page1.tif source=Corrective Assignment#page2.tif source=Corrective Assignment#page3.tif source=Corrective Assignment#page4.tif source=Corrective Assignment#page5.tif source=Corrective Assignment#page6.tif source=Corrective Assignment#page7.tif source=Corrective Assignment#page8.tif source=Corrective Assignment#page9.tif source=Corrective Assignment#page10.tif source=Corrective Assignment#page11.tif source=Corrective Assignment#page12.tif source=Corrective Assignment#page13.tif	

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application of:  
Jong Min Jang et al.

Application No.: Not Yet Assigned

Conf. No.: Not Yet Assigned

Filed: Herewith

For: WAFER LEVEL LIGHT-EMITTING DIODE ARRAY  
AND METHOD FOR MANUFACTURING SAME

**DECLARATION AND ASSIGNMENT BY THE INVENTOR  
UNDER RULE 37 C.F.R. § 1.63 EFFECTIVE ON SEPTEMBER 16, 2012**

As a below named inventor, I hereby declare that:

I believe I am the sole original inventor or an original joint inventor of a claimed invention in a patent application entitled:

**WAFER LEVEL LIGHT-EMITTING DIODE ARRAY AND METHOD FOR  
MANUFACTURING SAME**

filed on February 6, 2015, and assigned U.S. Application Number 14/420,175, the specification of which is attached hereto and identified as Attorney Docket No. 114896-8031.US00. I authorize and request an attorney appointed in the above-identified U.S. application to hereafter insert above the filing date and application number of the above-identified U.S. patent application when known.

I believe the following persons are original joint inventors of the above-identified U.S. patent application:

Jong Min Jang;

Jong Hyeon Chae;

Joon Sup Lee;

Daewoong Suh;

Won Young Roh;

Min Woo Kang; and

Hyun A Kim.

Inventors : Jong Min Jang et al.  
Appl. No. : Not Yet Assigned  
Filed : Herewith  
Page : 2 of 5

Docket No.: 114896-8031.US00

I made, authorized to make, or will make or authorize to make the above-identified patent application at the U.S. Patent and Trademark Office.

I have reviewed and understand the contents of the above-identified patent application including the claims.

I am aware of the duty to disclose to the U.S. Patent and Trademark Office all information known to me to be material to patentability as defined in 37 CFR §1.56.

I hereby acknowledge that any willful false statement made in the above declaration is punishable under 18 USC §1001 by fine or imprisonment of not more than five (5) years, or both.

#### ASSIGNMENT

I hereby assign to Seoul Viosys Co., Ltd., a corporation, having a place of business at 65-16, Sandan-ro 163 beon-gil, Danwon-gu, Ansan-si, Gyeonggi-do, Republic of Korea, and its successors and assigns (collectively "the Assignee"), the entire right, title and interest throughout the world in any and all inventions and improvements which are described in the above-identified application, and prior PCT Application No. PCT/KR2013/007091 and filed in the Republic of Korea Receiving Office on August 6, 2013, prior Korean Patent Application No. 10-2012-0086329 filed in the Republic of Korea on August 7, 2012, prior Korean Patent Application No. 10-2012-0094107 filed in the Republic of Korea on August 28, 2012, prior Korean Patent Application No. 10-2013-0088709 filed in the Republic of Korea on July 26, 2013, and prior Korean Patent Application No. 10-2013-0088710 filed in the Republic of Korea on July 26, 2013, from which the above-identified U.S. patent application claims priority and benefits.

This assignment includes the entire right, title and interest in the above-identified U.S. and Korean patent applications, all legal equivalents thereof in any country, any and all United States, Patent Cooperation Treaty, Republic of Korea and other foreign patents, utility models, and design registrations granted for any of said inventions and improvements, including, but not limited to, all divisions, continuations, reissues, reexamination certificates, any and all certificates issued in any post-grant proceeding, and extensions of said applications and patents of the United States, Patent Cooperation Treaty and Republic of Korea, all other foreign patents, utility models, and design registrations, and the right to claim priority based on the filing dates of

the above-identified U.S. and Republic of Korea patent applications under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes, and the right to seek relief and recover all damages, including, but not limited to, a reasonable royalty, by reason of infringement or any other violation of patent or patent application rights. I authorize the Assignee to apply in all countries in the name of the Assignee for patents, utility models, design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements.

In addition, I hereby confirm the sale, assignment, and transfer to the Assignee of the entire right, title and interest throughout the world in said inventions and improvements that occurred by operation of an employment agreement between me and the Assignee existing at the time said inventions and improvements were made. Should I have any remaining interest, I hereby sell, assign, and transfer any right, title and interest I may have in said inventions and improvements anywhere in the world to the Assignee.

The foregoing assignments, sale and transfer have been made for good and valuable consideration in accordance with the aforementioned employment agreement.

I hereby represent and covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into that would conflict with the assignment of said inventions and improvements to the Assignee.

I further covenant for myself and my respective heirs, legal representatives and assigns, to assist the Assignee in handling various procedures, tasks and documentation in connection with this assignment, including, but not limited to, providing to the Assignee promptly upon the request of the Assignee all pertinent facts and documents relating to said invention and improvements, and said patents, said legal equivalents or other legal instrument as may be known and accessible to me and testifying as to the same in any interference, litigation, or proceeding relating thereto, and promptly executing and delivering to the Assignee or its legal representative any and all papers, documents, instruments or affidavits in connection with obtaining, maintaining, issuing or enforcing said application, said inventions and improvements, and said patents, said equivalents and other legal instrument which may be necessary or desirable to carry out the purposes thereof.

Inventors : Jong Min Jang et al.  
Appl. No. : Not Yet Assigned  
Filed : Herewith  
Page : 4 of 5

Docket No.: 114896-8031.US00

I hereby authorize and request the Commissioner of Patents and Trademarks to issue one or more patents in the United States for said inventions and improvements to Seoul Viosys Co., Ltd. as assignee of the entire interest, for the sole use and benefit of Assignee, its successors and assigns.

I am competent to execute the above declaration and assignment. I hereby have duly executed the declaration and assignment below with my name.

Full name of first inventor: Jong Min Jang

Inventor's signature: Jong Min Jang

Date: Jan. 24<sup>th</sup>, 2015

Full name of joint inventor: Jong Hyeon Chae

Inventor's signature: Jong Hyeon Chae

Date: Jan. 21<sup>th</sup>, 2015

Full name of joint inventor: Joon Sup Lee

Inventor's signature: Joon Sup Lee

Date: Jan 24<sup>th</sup> 2015

Full name of joint inventor: Daewoong Suh

Inventor's signature: Daewoong Suh

Date: Feb 2<sup>nd</sup>, 2015

Full name of joint inventor: Won Young Roh

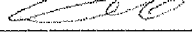
Inventor's signature: Won Young Roh

Date: Jan. 21<sup>th</sup>, 2015

Inventors : Jong Min Jang et al.  
Appl. No. : Not Yet Assigned  
Filed : Herewith  
Page : 5 of 5

Docket No.: 114896-8031.US00

Full name of joint inventor: Min Woo Kang

Inventor's signature: 

Date: Jan. 21<sup>st</sup>, 2015

Full name of joint inventor: Hyun A Kim

Inventor's signature: 김현아

Date: Jan 21<sup>st</sup>, 2015

Perkins Coie LLP  
P.O. Box 1247  
Seattle, Washington 98111-1247  
Telephone: (858) 720-5700  
Facsimile: (206) 359-7198

APPLICATION NUMBER: 14420175

FILING DATE:

PATENT NUMBER:

ISSUE DATE:

TITLE: WAFER LEVEL LIGHT-EMITTING DIODE ARRAY AND METHOD FOR  
MANUFACTURING SAME

ASSIGNMENT RECORDATION BRANCH  
PUBLIC RECORDS DIVISION



<b>PATENT ASSIGNMENT COVER SHEET</b>
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Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT3231475

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
JONG MIN JANG	01/21/2015
JONG HYEON CHAE	01/21/2015
JOON SUP LEE	01/21/2015
DAEWOONG SUH	02/02/2015
WON YOUNG ROH	01/21/2015
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SEOUL VIOSYS CO., LTD.
<b>Street Address:</b>	65-16, SANDAN-RO 163 BEON-GIL
<b>Internal Address:</b>	DANWON-GU, GYEONGGI-DO
<b>City:</b>	ANSAN-SI
<b>State/Country:</b>	KOREA, REPUBLIC OF
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	14420175
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(858)720-5819
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	(858)720-5700
<b>Email:</b>	michellemelendez@perkinscoie.com
<b>Correspondent Name:</b>	BING AI
<b>Address Line 1:</b>	PERKINS COIE LLP
<b>Address Line 2:</b>	PO BOX 1247
<b>Address Line 4:</b>	SEATTLE, WASHINGTON 98111-1247
<b>ATTORNEY DOCKET NUMBER:</b>	114896-8031.US00
<b>NAME OF SUBMITTER:</b>	MICHELLE MELENDEZ
<b>SIGNATURE:</b>	/Michelle Melendez/
<b>DATE SIGNED:</b>	02/18/2015
This document serves as an Oath/Declaration (37 CFR 1.63).	

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In re Patent Application of:  
Jong Min Jang et al.

Application No.: Not Yet Assigned

Conf. No.: Not Yet Assigned

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Inventors : Jong Min Jang et al.  
Appl. No. : Not Yet Assigned  
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Page : 4 of 5

Docket No.: 114896-8031.US00

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Full name of joint inventor: Joon Sup Lee

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Full name of joint inventor: Daewoong Suh

Inventor's signature: Daewoong Suh

Date: Feb 2<sup>nd</sup>, 2015

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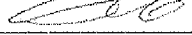
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Inventors : Jong Min Jang et al.  
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Page : 5 of 5

Docket No.: 114896-8031.US00

Full name of joint inventor: Min Woo Kang

Inventor's signature: 

Date: Jan. 21<sup>st</sup>, 2015

Full name of joint inventor: Hyun A Kim

Inventor's signature: 김현아

Date: Jan 21<sup>st</sup>, 2015

Perkins Coie LLP  
P.O. Box 1247  
Seattle, Washington 98111-1247  
Telephone: (858) 720-5700  
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